

HSEC8-149-01-L-DV-A

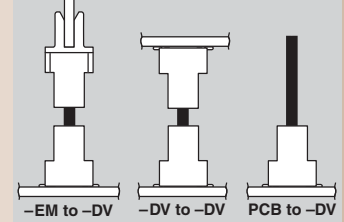


RUGGEDIZED
by SAMTEC
• Board lock option
• Latch option

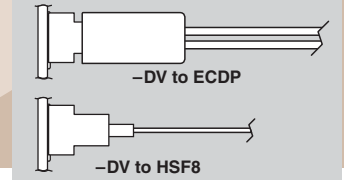
(0,80mm) .0315"
HSEC8-DV SERIES

VERTICAL EDGE RATE™ CARD SOCKET

BOARD-TO-BOARD APPLICATIONS



HIGH SPEED CABLE & FLEX APPLICATIONS



SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DV

Insulator Material:

Black Liquid Crystal Polymer



Contact:

BeCu



Plating:

Au or Sn over 50µ" (1,27µm) Ni

Current Rating:

3.1A @ 30°C Temperature Rise (See website for details)

Operating Temp:

-55°C to +125°C

Card Insertion Depth:

(3,15mm) .125" nominal

RoHS Compliant:

Yes

Processing:

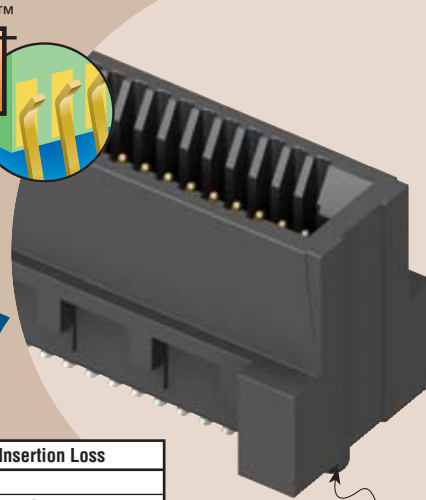
Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10mm) .004" max (10-60)

Mates with:
1,60mm thick cards,
ECDP, HSC8, HSF8

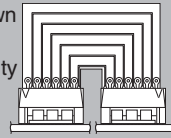


Alignment Pins

0,80mm HSEC8	Rated @ 3dB Insertion Loss
7,98mm Stack Height	
Single-Ended Signaling	8 GHz / 16 Gbps
Differential Pair Signaling	10.5 GHz / 21 Gbps
For complete test data go to www.samtec.com?HSEC8-DV or contact sig@samtec.com	

STANDARD & CUSTOM CARDS AVAILABLE

- Standard high speed interface cards for 19mm, 25mm & 30mm mated heights, single-ended & differential applications. See HSC8 Series.
- Custom cards for low-cost stack height customization
- Samtec supplied card layout/artwork to make your own cards
- Specialty card shapes



APPLICATION SPECIFIC OPTION

Guide rails and pass-through options. Call Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.



10, 13, 20, 25, 30, 37, 40, 49, 50, 60

No. of Positions x (0,80) .0315 + (4,60) .181

(0,80) .0315

-01
= (1,60mm) .062" thick card

-03
= (2,36mm) .093" thick card

-L
= 10µ" (0,25µm) Gold on contact, Matte Tin on tail

Note: Other Gold plating options available. Contact Samtec.

-K
= (5,50mm) .217" DIA Polyimide Film Pick & Place Pad

-TR
= Tape & Reel Packaging

-L1
= Latching Option (For use with ECDP.) (13, 25, 37, 49 only)

-BL
= Board Locks (40, 50, 60 only) (Other sizes available. Contact Samtec.)

-WT
= Weld tab

10, 20 & 30

BL L1

CARD THICKNESS	A	B	C
-01	(1,75) .070	(5,60) .220	(7,00) .276
-03	(2,54) .100	(6,39) .252	(7,79) .307

POSITIONS PER ROW	D	E
13*	(6,10) .240	(15,00) .591
25*	(6,10) .240	(24,60) .969
37*	(18,10) .713	(34,20) 1.346
40	(18,90) .744	(36,60) 1.441
49*	(22,90) .902	(43,80) 1.724
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071

Positions where no dimensions are given do not have keying feature.
*Mates with ECDP Series.

CONNECTOR	CABLE*
HSEC8-113	ECDP-08
HSEC8-125	ECDP-16
HSEC8-137	ECDP-24
HSEC8-149	ECDP-32

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM